

Full Wafer & Singulated Die / Module Test System

Compact High Power Test and Reliability Verification Solution for Logic, Memory and Photonic Devices



SYSTEM BENEFITS

- **Compact Flexible Solution for High Throughput Reliability Verification and Test**
 - ◆ Handles full wafer, panel, singulated die and module applications
 - ◆ Identifies failing logic, memory and photonic die before final package integration
 - ◆ High power thermal chuck dual Blade (slot) capability using WaferPakTM contactors or DiePak[®] carriers (for singulated die and modules)
- **Cost-Effective Solution for High Power Wafer/Die/Module Verification and Test**
 - ◆ Configurable channel resources per Blade: Universal Channel Modules, High Voltage Channel Modules or High Current Channel Modules
 - ◆ Up to 2,048 "Universal Channel" resources: (I/O, Clock, PPMU or DPS) per Blade with deep scan, pattern data and capture memory for testing of devices with BIST or DFT capabilities
 - ◆ Up to 1,024 high voltage (29 V) or high current (2 A) sources resources per Blade
- **Production Proven Full-Wafer Reliability Verification & Test Solution**
 - ◆ Reduces test costs by functionally testing wafers, die or modules during reliability verification
 - ◆ Offers a total solution when configured with a WaferPak contactor, DiePak carrier, Wafer Aligner and DiePak Loader
 - ◆ Protects devices with individual per channel over-current and over-voltage protection

"Setting the Test Standard for Tomorrow"

CORPORATE HEADQUARTERS

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